



**Terminal Disclaimer To Obviate A Double  
Patenting Rejection Over A Prior Patent**

Docket No.  
08CN7392-2

In Re Application Of: **Zarnoch et al.**

Serial No.  
09/681,376

Filing Date  
3/27/2001

Examiner  
Short, Patricia A.

Group Art Unit  
1712

Invention: **POLY(ARYLENE ETHER)-CONTAINING THERMOSET COMPOSITION IN POWDER FORM,  
METHOD FOR THE PREPARATION THEREOF, AND ARTICLES DERIVED THEREFROM**

Owner of Record: **General Electric Company**

**TO THE COMMISSIONER FOR PATENTS:**

The above-identified owner of record of a **100** percent interest in the instant application hereby disclaims, except as provided below, the terminal part of the statutory term of any patent granted on the instant application, which would extend beyond the expiration date of the full statutory term defined in 35 U.S.C. 154 to 156 and 173, as presently shortened by any terminal disclaimer, of prior Patent No. **6,593,391**. The owner hereby agrees that any patent so granted on the instant application shall be enforceable only for and during such period that it and the prior patent are commonly owned. This agreement runs with any patent granted on the instant application and is binding upon the grantee, its successors and/or assigns.

In making the above disclaimer, the owner does not disclaim the terminal part of any patent granted on the instant application that would extend to the expiration date of the full statutory term as defined in 35 U.S.C. 154 to 156 and 173 of the prior patent, as presently shortened by any terminal disclaimer, in the event that it later expires for failure to pay a maintenance fee, is held unenforceable, is found invalid by a court of competent jurisdiction, is statutorily disclaimed in whole or terminally disclaimed under 37 C.F.R. 1.321, has all claims cancelled by a reexamination certificate, is reissued, or is in any manner terminated prior to the expiration of its full statutory term as presently shortened by any terminal disclaimer.

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

2. ☒ The undersigned is an attorney of record.

  
Signature

Dated: **April 16, 2004**

**J. Michael Buchanan, Reg. No. 44,571**

*Typed or Printed Name*

- ☒ Terminal disclaimer fee under 37 C.F.R. 1.20(d) included.  
☒ PTO suggested wording for terminal disclaimer was unchanged.  
☐ Certification under 37 C.F.R. 3.73(b) is required if terminal disclaimer is signed by the assignee.

**CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)**Applicant(s): **Zarnoch et al.**

Docket No.

**08CN7392-2**

Serial No.

**09/681,376**

Filing Date

**3/27/2001**

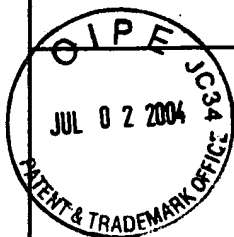
Examiner

**Short, Patricia A.**

Group Art Unit

**1712**

Invention: **POLY(ARYLENE ETHER)-CONTAINING THERMOSET COMPOSITION IN POWDER FORM,  
METHOD FOR THE PREPARATION THEREOF, AND ARTICLES DERIVED THEREFROM**



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# FEE TRANSMITTAL for FY 2004

Effective 10/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT (\$) \$110.00

## Complete if Known

Application Number 09/681,376

Filing Date 3/27/2001

First Named Inventor Zarnoch et al.

Examiner Name Short, Patricia A.

Art Unit 1712

Attorney Docket No. 08CN7392-2

## METHOD OF PAYMENT (check all that apply)

☐ Check ☐ Credit card ☐ Money Order ☐ Other ☐ None

☒ Deposit Account:

Deposit  
Account  
Number

07-0862

Deposit  
Account  
Name

General Electric Company

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☐ Credit any overpayments

☐ Charge any additional fee(s) or any underpayment of fee(s)

☐ Charge fee(s) indicated below, except for the filing fee  
to the above-identified deposit account.

## FEE CALCULATION

### 1. BASIC FILING FEE

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
1001	770	2001	385	Utility filing fee	
1002	340	2002	170	Design filing fee	
1003	530	2003	265	Plant filing fee	
1004	770	2004	385	Reissue filing fee	
1005	160	2005	80	Provisional filing fee	
SUBTOTAL (1)					(\$)

### 2. EXTRA CLAIM FEES FOR UTILITY AND

Total Claims		Extra Claims		Fee from below	Fee Paid
		-20** =	0	X	0.00
Independent Claims		-3** =	0	X	0.00
Multiple Dependent					

Large Entity		Small Entity		Fee Description
Fee Code	Fee (\$)	Fee Code	Fee (\$)	
1202	18	2202	9	Claims in excess of 20
1201	86	2201	43	Independent claims in excess of 3
1203	290	2203	145	Multiple dependent claim, if not paid
1204	86	2204	43	** Reissue independent claims over original patent
1205	18	2205	9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$) \$0.00

\*\*or number previously paid, if greater; For Reissues, see above

## FEE CALCULATION (continued)

### 3. ADDITIONAL FEES

Large Entity		Small Entity		Fee Description	Fee Paid
Fee Code	Fee (\$)	Fee Code	Fee (\$)		
1051	130	2051	65	Surcharge - late filing fee or oath	
1052	50	2052	25	Surcharge - late provisional filing fee or cover sheet	
1053	130	1053	130	Non - English specification	
1812	2,520	1812	2,520	For filing a request for ex parte reexamination	
1804	920*	1804	920*	Requesting publication of SIR prior to Examiner action	
1805	1,840*	1805	1,840*	Requesting publication of SIR after Examiner action	
1251	110	2251	55	Extension for reply within first month	
1252	420	2252	210	Extension for reply within second month	
1253	950	2253	475	Extension for reply within third month	
1254	1,480	2254	740	Extension for reply within fourth month	
1255	2,010	2255	1,005	Extension for reply within fifth month	
1401	330	2401	165	Notice of Appeal	
1402	330	2402	165	Filing a brief in support of an appeal	
1403	290	2403	145	Request for oral hearing	
1451	1,510	1451	1,510	Petition to institute a public use proceeding	
1452	110	2452	55	Petition to revive - unavoidable	
1453	1,330	2453	665	Petition to revive - unintentional	
1501	1,330	2501	665	Utility issue fee (or reissue)	
1502	480	2502	240	Design issue fee	
1503	640	2503	320	Plant issue fee	
1460	130	1460	130	Petitions to the Commissioner	
1807	50	1807	50	Processing fee under 37 CFR § 1.17(q)	
1806	180	1806	180	Submission of Information Disclosure Statement	
8021	40	8021	40	Recording each patent assignment per property (times number of properties)	
1809	770	2809	385	Filing a submission after final rejection (37 CFR § 1.129(a))	
1810	770	2810	385	For each additional invention to be examined (37 CFR § 1.129(b))	
1801	770	2801	385	Request for Continued Examination (RCE)	
1802	900	1802	900	Request for expedited examination of a design application	
Other fee (specify) Terminal Disclaimer					110.00

\*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$) \$110.00

## SUBMITTED BY

Name (Print/Type)	J. Michael Buchanan	Registration No. (Attorney/Agent)	44,571	Telephone	860-286-2929
Signature	Michael Buchanan	Date	April 16, 2004		

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This collection of information is required by 37 CFR 1.17 and 1.27. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.



US006593391B2

(12) **United States Patent**  
**Teutsch et al.**

(10) **Patent No.:** **US 6,593,391 B2**  
**(45) Date of Patent:** **Jul. 15, 2003**

- (54) **ABRASIVE-FILLED THERMOSET COMPOSITION AND ITS PREPARATION, AND ABRASIVE-FILLED ARTICLES AND THEIR PREPARATION**
- (75) **Inventors:** Erich Otto Teutsch, Richmond, MA (US); Gary William Yeager, Schenectady, NY (US); Kenneth Paul Zarnoch, Scotia, NY (US); Steven William Webb, Worthington, OH (US); Hua Guo, Selkirk, NY (US)
- (73) **Assignee:** General Electric Company, Pittsfield, MA (US)
- (\*) **Notice:** Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

(21) **Appl. No.:** 09/681,381

(22) **Filed:** Mar. 27, 2001

(65) **Prior Publication Data**

US 2003/0018116 A1 Jan. 23, 2003

- (51) **Int. Cl.<sup>7</sup>** ..... C08F 2/46
- (52) **U.S. Cl.** ..... 522/81; 522/71; 522/73; 522/83; 522/77; 522/167; 522/160; 522/134; 522/135; 522/142; 522/144; 524/430; 524/432; 524/433; 524/436; 524/437; 524/438; 524/440; 524/441; 525/132; 525/390; 525/391; 525/397; 528/137; 528/138; 528/139; 528/154; 528/159; 528/160; 528/161
- (58) **Field of Search** ..... 522/71, 73, 81, 522/83, 77, 167, 160, 134, 135, 137, 142, 144; 524/430, 432, 433, 434, 436, 437, 438, 440, 441; 525/132, 390, 391, 392, 397, 137, 161, 138, 139, 154, 159, 160; 428/688, 694 BC, 698, 704, 543, 694 BG

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

3,219,625 A 11/1965 Blanchard et al.  
 3,268,561 A 8/1966 Peppel et al.  
 3,306,875 A 2/1967 Hay  
 3,375,228 A 3/1968 Holoch et al.  
 3,557,045 A 1/1971 Wright et al.  
 3,597,216 A 8/1971 Berardinelli et al.  
 3,637,578 A 1/1972 Wright et al.  
 3,883,612 A 5/1975 Pratt et al.  
 3,936,414 A 2/1976 Wright et al.  
 3,960,516 A 6/1976 Biardi  
 4,028,341 A 6/1977 Hay  
 4,048,143 A 9/1977 Hay et al.  
 4,054,425 A 10/1977 Sherman  
 4,088,729 A 5/1978 Sherman  
 4,092,294 A 5/1978 Bennett, Jr. et al.  
 4,148,843 A 4/1979 Goossens  
 4,165,422 A 8/1979 White  
 4,327,013 A 4/1982 Peters  
 4,440,923 A 4/1984 Bartmann et al.  
 RE31,883 E 5/1985 Bovenkerk et al.  
 4,562,243 A 12/1985 Percec  
 4,565,684 A 1/1986 Tibbets et al.

4,572,813 A 2/1986 Arakawa  
 4,604,417 A 8/1986 Cottman  
 4,618,703 A 10/1986 Thanawalla et al.  
 4,634,742 A 1/1987 Percec  
 4,663,230 A 5/1987 Tennent  
 4,663,402 A 5/1987 Percec et al.  
 4,665,137 A 5/1987 Percec  
 4,677,185 A 6/1987 Heitz et al.  
 4,701,514 A 10/1987 Percec  
 4,760,118 A 7/1988 White et al.  
 H521 H 9/1988 Fan  
 4,806,601 A 2/1989 Percec  
 4,816,289 A 3/1989 Komatsu et al.  
 4,816,515 A 3/1989 Weiss  
 4,871,816 A 10/1989 Percec et al.  
 4,874,826 A 10/1989 Sakamoto et al.  
 4,876,078 A 10/1989 Arakawa et al.  
 4,888,397 A 12/1989 van der Meer et al.  
 4,923,932 A 5/1990 Katayose et al.  
 5,024,818 A 6/1991 Tibbets et al.  
 5,039,781 A 8/1991 Neugebauer et al.  
 5,061,602 A 10/1991 Koch et al.  
 5,071,922 A 12/1991 Nelissen et al.

(List continued on next page.)

**FOREIGN PATENT DOCUMENTS**

DE 31 17 514 A1 2/1981  
 DE 41 03 140 A1 2/1991  
 EP 0 385 065 A1 2/1991  
 EP 0 261 574 B1 11/1991  
 EP 0 498 088 A1 11/1991  
 EP 0 794 850 B1 5/1999  
 JP 08 012875 A 1/1996  
 NL 8902092 8/1989  
 WO WO 01/40354 A1 7/2001

**OTHER PUBLICATIONS**

Derwent Abstract for JP08-245872.  
 U.S. Patent Application, Attorney Docket No. 08CN8786-11, Filed on Jul. 2, 2002, 90 pages (Serial No. not yet assigned).  
 U.S. patent application Ser. No. 09/681,376, Zarnoch et al., pending.  
 U.S. patent application Ser. No. 09/683,214, Yeager et al., pending.  
 U.S. patent application Ser. No. 09/683,352, Braat et al., pending.  
 Coleen Pugh and V. Percec, "Group Transfer Polymerization of Some Unusual Acrylates and Methacrylates", Polym. Prepr. (Am. Chem. Soc., Div. Polym. Chem.), (1985), 26(2), 303-5.

*Primary Examiner*—James J. Seidleck  
*Assistant Examiner*—Sanza L. McClendon

(57) **ABSTRACT**

A curable resin composition comprises a poly(arylene ether), an acryloyl monomer, an allylic monomer, and an abrasive filler. The composition tolerates high filler contents, cures rapidly, and exhibits excellent toughness after curing. Useful articles prepared from the composition include grinding wheels and cut-off wheels having good wear characteristics.

**50 Claims, No Drawings**

## U.S. PATENT DOCUMENTS

5,079,268 A	1/1992	Nelissen et al.	5,407,972 A	4/1995	Smith et al.
5,091,480 A	2/1992	Percec	5,589,152 A	12/1996	Tennent et al.
5,118,748 A	6/1992	Fujita et al.	5,591,382 A	1/1997	Nahass et al.
5,165,909 A	11/1992	Tennent et al.	5,834,565 A	11/1998	Tracy et al.
5,167,674 A	12/1992	Ika	5,851,646 A	12/1998	Takahashi et al.
5,171,761 A	12/1992	Penco et al.	5,885,149 A	3/1999	Gillet et al.
5,200,122 A	4/1993	Katoh et al.	5,922,815 A	7/1999	Aycock et al.
5,213,886 A	5/1993	Chao et al.	5,965,663 A	10/1999	Hayase
5,218,030 A	6/1993	Katayose et al.	6,022,550 A	2/2000	Watanabe
5,219,951 A	6/1993	Nelissen et al.	6,306,963 B1	10/2001	Lane et al.
5,240,973 A	8/1993	Katoh et al.	6,352,782 B2 *	3/2002	Yeager et al. .... 428/457
5,304,600 A	4/1994	Nelissen et al.	6,384,176 B1	5/2002	Braat et al.
5,306,318 A	4/1994	Carius et al.	2001/0049046 A1	12/2001	Butler ..... 429/34
5,310,820 A	5/1994	Nelissen et al.	2001/0053820 A1	12/2001	Yeager et al.
5,314,512 A	5/1994	Sexton	2002/0005508 A1	1/2002	Butler et al. .... 252/500
5,338,796 A	8/1994	Vianello et al.	2002/0028337 A1	3/2002	Yeager et al.
5,352,745 A *	10/1994	Katayose et al. .... 428/461	2002/0077447 A1	6/2002	Hwang et al.

\* cited by examiner

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# ABRASIVE-FILLED THERMOSET COMPOSITION AND ITS PREPARATION, AND ABRASIVE-FILLED ARTICLES AND THEIR PREPARATION

## BACKGROUND OF INVENTION

Abrasive-filled resins are known and employed in the fabrication of abrasive tools such as cutting and grinding wheels. Grinding wheels containing superabrasive materials (e.g., diamond or cubic boron nitride, CBN) in the edge or outer periphery of a circular grinding wheel or grinding cup also are well-known in the fields of sawing, drilling, dressing, grinding, lapping, polishing, and other abrading applications. For these applications, the grit typically is surrounded in a matrix of a metal, such as Ni, Cu, Fe, Co, Sn, W, Ti, or an alloy thereof, or in a resin, such as phenol formaldehyde or other thermosetting polymeric material. By attaching the matrices to a body or other support, tools may be fabricated having the capability to cut through such hard, abrasive materials as concrete, asphalt, masonry, ceramic, brick, granite, marble, and other rock. A typical such wheel is formed from a central metal disk having an aperture or a spindle for spinning the wheel in use. The outer periphery of the wheel, then, has a diamond-containing matrix bonded thereto. For wheels where the diamond is surrounded by a resin, the operator often cures the resin and bonds the resinous segments to the inner wheel by compression molding. Conventional bonding resins are used.

U.S. Pat. No. 5,167,674 describes grinding wheels manufactured from a conventional inner core to which is adhesively bonded a mixture of superabrasive grit, a bis-maleimide-triazine addition copolymer resin, free-radical initiator, and catalyst. This mixture is compression molded to form a grinding segment annulus.

U.S. Pat. No. 5,314,512 describes injection molding of saw segments from superabrasive particles and a non-porous thermoplastic polymer. The molded saw segments then are affixed to the periphery of a saw blade.

European Patent No. 794,850 B1 describes cutting segments manufactured from superabrasive particles molded with a thermoplastic material wherein the superabrasive particles are oriented in a chosen direction and there is porosity in the molded segments.

U.S. Pat. Nos. 4,054,425 and 4,088,729 describe molding a hub into a phenol-based thermoplastic resin-grinding wheel.

U.S. Pat. No. 3,960,516 describes manufacturing a grinding cup wherein the supporting part is molded as a part of the grinding cup to ensure a secure attachment.

There is a need for curable, abrasive-filled resin compositions that allow fast preparation of cutting and grinding tools having improved wear characteristics.

## SUMMARY OF INVENTION

Disclosed herein are several embodiments of a resin composition, its reaction product, a method for its preparation, and articles derived from it.

In one embodiment, a curable resin composition comprises a poly(arylene ether), an acryloyl monomer, an allylic monomer, and an abrasive filler.

In another embodiment, a cured resin composition comprises the reaction product of a poly(arylene ether), an acryloyl monomer, an allylic monomer, and an abrasive filler.

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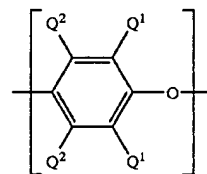
Yet another embodiment is a method of preparing the curable resin composition.

Still other embodiments are articles comprising the cured resin composition and methods for their preparation.

## DETAILED DESCRIPTION

A curable resin composition comprises a poly(arylene ether), an acryloyl monomer, an allylic monomer, and an abrasive filler.

The composition may comprise any poly(arylene ether). The term poly(arylene ether) includes polyphenylene ether (PPE) and poly(arylene ether) copolymers; graft copolymers; poly(arylene ether) ether ionomers; and block copolymers of alkenyl aromatic compounds, vinyl aromatic compounds, and poly(arylene ether), and the like; and combinations comprising at least one of the foregoing; and the like. Poly(arylene ether)s are known polymers comprising a plurality of structural units of the formula:



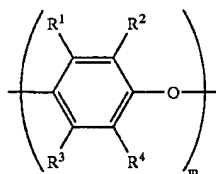
wherein for each structural unit, each Q<sup>1</sup> is independently halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarbonoxy, or C<sub>2</sub>-C<sub>12</sub> halohydrocarbonoxy wherein at least two carbon atoms separate the halogen and oxygen atoms; and each Q<sup>2</sup> is independently hydrogen, halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarbonoxy, or C<sub>2</sub>-C<sub>12</sub> halohydrocarbonoxy wherein at least two carbon atoms separate the halogen and oxygen atoms. Preferably, each Q<sup>1</sup> is independently C<sub>1</sub>-C<sub>12</sub> alkyl or phenyl, especially C<sub>1-4</sub> alkyl, and each Q<sup>2</sup> is independently hydrogen or methyl.

Both homopolymer and copolymer poly(arylene ether)s are included. In one embodiment, the poly(arylene ether) is a homopolymer comprising 2,6-dimethyl-1,4-phenylene ether units. Suitable copolymers include random copolymers comprising, for example, such units in combination with 2,3,6-trimethyl-1,4-phenylene ether units or copolymers derived from copolymerization of 2,6-dimethylphenol with 2,3,6-trimethylphenol. Also included are poly(arylene ether)s containing moieties prepared by grafting vinyl monomers or polymers such as polystyrenes, as well as coupled poly(arylene ether) in which coupling agents such as low molecular weight polycarbonates, quinones, heterocycles and formals undergo reaction with the hydroxy groups of two poly(arylene ether) chains to produce a higher molecular weight polymer. Poly(arylene ether)s further include combinations of any of the above.

The poly(arylene ether)s are typically prepared by the oxidative coupling of at least one monohydroxyaromatic compound such as 2,6-xyleneol or 2,3,6-trimethylphenol. Catalyst systems are generally employed for such coupling; they typically contain at least one heavy metal compound such as a copper, manganese or cobalt compound, usually in combination with various other materials. Suitable methods for the preparation and isolation of poly(arylene ether)s are disclosed in, for example, U.S. Pat. Nos. 3,219,625 to Blanchard et al., 3,306,875 to Hay, 4,028,341 to Hay,

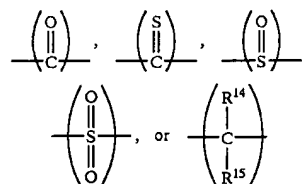
In one embodiment, the composition comprises a poly(arylene ether) having less than 500 parts per million (ppm) of free hydroxyl groups. In other words, the poly(arylene ether) contains less than 500 micrograms of hydroxyl groups (as —OH) per gram of poly(arylene ether). The poly(arylene ether) preferably comprises less than 300 ppm of free hydroxyl groups, more preferably less than 100 ppm of free hydroxyl groups.

The capped poly(arylene ether) may be represented by the structure Q-(J-K)<sub>y</sub> wherein Q is the residuum of a monohydric, dihydric, or polyhydric phenol, preferably the residuum of a monohydric or dihydric phenol, more preferably the residuum of a monohydric phenol; y is 1 to 100; J comprises recurring units having the structure

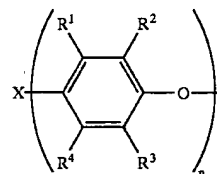

$$\text{---Y---R}^5, \left( \text{---Y---} \begin{array}{c} \text{R}^6 \\ \text{C} \\ \text{R}^7 \\ \text{R}^8 \end{array} \right), \text{ and}$$

$$\text{---Y---} \begin{array}{c} \text{R}^9 \\ \text{C}_6\text{H}_2 \\ \text{R}^{10} \\ \text{R}^{11} \\ \text{R}^{12} \\ \text{R}^{13} \end{array}$$

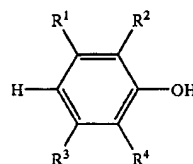
4



In one embodiment, Q is the residuum of a phenol, including polyfunctional phenols, and includes radicals of the structure

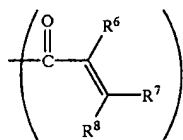


In one embodiment, the capped poly(arylene ether) is produced by capping a poly(arylene ether) consisting essentially of the polymerization product of at least one monohydric phenol having the structure



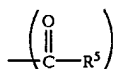
In one embodiment, the capped poly(arylene ether) comprises at least one capping group having the structure

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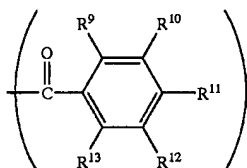
wherein  $R^6$ - $R^8$  are each independently hydrogen,  $C_1$ - $C_{12}$  alkyl,  $C_2$ - $C_{12}$  alkenyl,  $C_6$ - $C_{18}$  aryl,  $C_7$ - $C_{18}$  mixed (alkyl-aryl),  $C_2$ - $C_{12}$  alkoxy carbonyl,  $C_7$ - $C_{18}$  aryloxy carbonyl,  $C_8$ - $C_{18}$  mixed (alkyl-aryl)oxy carbonyl, nitrile, formyl, carboxylate, imide, thiocarboxylate, or the like. Highly preferred capping groups include acrylate ( $R^6=R^7=R^8$ =hydrogen) and methacrylate ( $R^6$ =methyl,  $R^7=R^8$ =hydrogen).

In one embodiment, the capped poly(arylene ether) comprises at least one capping group having the structure



wherein  $R^5$  is  $C_1$ - $C_{12}$  alkyl, preferably  $C_1$ - $C_6$  alkyl, more preferably methyl, ethyl, or isopropyl. It has surprisingly been found that the advantageous properties of the composition can be achieved even when the capped poly(arylene ether) lacks a polymerizable function such as a carbon-carbon double bond.

In another embodiment, the capped poly(arylene ether) comprises at least one capping group having the structure



wherein  $R^9$ - $R^{13}$  are each independently hydrogen, halogen,  $C_1$ - $C_{12}$  alkyl, hydroxy, amino, or the like. Preferred capping groups of this type include salicylate ( $R^9$  is hydroxy, and  $R^{10}$ - $R^{13}$  are hydrogen).

In one embodiment, the capped poly(arylene ether) is substantially free of amino substituents, including alkylamino and dialkylamino substituents, wherein substantially free means that the capped poly(arylene ether) contains less than about 300 micrograms, preferably less than about 200 micrograms, more preferably less than about 100 micrograms, of atomic nitrogen per gram of capped poly(arylene ether). Although many poly(arylene ether)s are synthesized by processes that result in the incorporation of amino substituents, it has been discovered that thermoset curing rates are increased when the capped poly(arylene ether) is substantially free of amino substituents. Poly(arylene ether)s substantially free of amino substituents may be synthesized directly or generated by heating amino-substituted poly(arylene ether)s to at least about 200° C. Alternatively, if the capped poly(arylene ether) contains amino substituents, it may be desirable to cure the composition at a temperature less than about 200° C.

There is no particular limitation on the method by which the capped poly(arylene ether) is prepared. The capped poly(arylene ether) may be formed by the reaction of an uncapped poly(arylene ether) with a capping agent. Capping agents include compounds that react with phenolic groups.

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Such compounds include both monomers and polymers containing, for example, anhydride groups, acid chloride groups, epoxy groups, carbonate groups, ester groups, isocyanate groups, cyanate ester groups, alkyl halide groups, or combinations comprising at least one of the foregoing groups. Capping agents are not limited to organic compounds as, for example, phosphorus and sulfur based capping agents also are included. Examples of capping agents include, for example, acetic anhydride, succinic anhydride, maleic anhydride, salicylic anhydride, polyesters comprising salicylate units, homopolyesters of salicylic acid, acrylic anhydride, methacrylic anhydride, glycidyl acrylate, glycidyl methacrylate, acetyl chloride, benzoyl chloride, diphenyl carbonates such as di(4-nitrophenyl)carbonate, acryloyl esters, methacryloyl esters, acetyl esters, phenylisocyanate, 3-isopropenyl- $\alpha$ , $\alpha$ -dimethylphenylisocyanate, cyanatobenzene, 2,2-bis(4-cyanatophenyl)propane, 3-( $\alpha$ -chloromethyl)styrene, 4-( $\alpha$ -chloromethyl)styrene, allyl bromide, and the like, carbonate and substituted derivatives thereof, and mixtures comprising at least one of the foregoing capping agents. These and other methods of forming capped poly(arylene ether)s are described, for example, in U.S. Pat. Nos. 3,375,228 to Holoch et al.; 4,148,843 to Goossens; 4,562,243, 4,663,402, 4,665,137, and 5,091,480 to Percec et al.; 5,071,922, 5,079,268, 5,304,600, and 5,310,820 to Nelissen et al.; 5,338,796 to Vianello et al.; and European Patent No. 261,574 B1 to Peters et al.

A capping catalyst may be employed in the reaction of an uncapped poly(arylene ether) with an anhydride. Examples of such compounds include those that are capable of catalyzing condensation of phenols with the capping agents described above. Useful materials are basic compounds including, for example, basic compound hydroxide salts such as sodium hydroxide, potassium hydroxide, tetraalkylammonium hydroxides, and the like; tertiary alkyl amines such as tributyl amine, triethylamine, dimethylbenzylamine, dimethylbutylamine, and the like; tertiary mixed alkyl-arylamines and substituted derivatives thereof such as dimethylaniline, and the like; heterocyclic amines such as imidazoles, pyridines, and substituted derivatives thereof such as 2-methylimidazole, 2-vinylimidazole, 4-(dimethylamino)pyridine, 4-(1-pyrrolino)pyridine, 4-(1-piperidino)pyridine, 2-vinylpyridine, 3-vinylpyridine, 4-vinylpyridine, and the like; and mixtures comprising at least one of the foregoing materials. Also useful are organometallic salts such as, for example, tin and zinc salts known to catalyze the condensation of, for example, isocyanates or cyanate esters with phenols. The organometallic salts useful in this regard are known to the art in numerous publications and patents well known to those skilled in this art.

The composition may comprise a blend of at least two capped poly(arylene ethers). Such blends may be prepared from individually prepared and isolated capped poly(arylene ethers). Alternatively, such blends may be prepared by reacting a single poly(arylene ether) with at least two capping agents.

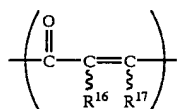
There is no particular limitation on the molecular weight or intrinsic viscosity of the poly(arylene ether). In one embodiment, the intrinsic viscosity, as measured by chloroform at 25° C., may be at least about 0.1 deciliters/gram (dL/g), preferably at least about 0.15 dL/g, more preferably at least about 0.20 dL/g. The intrinsic viscosity may be up to about 0.50 dL/g, preferably up to about 0.45 dL/g, more preferably up to about 0.40 dL/g, yet more preferably up to about 0.35 dL/g. Generally, the intrinsic viscosity of a capped poly(arylene ether) will vary insignificantly from the



intrinsic viscosity of the corresponding uncapped poly (arylene ether). It is expressly contemplated to employ blends of at least two capped poly(arylene ether)s having different molecular weights and intrinsic viscosities.

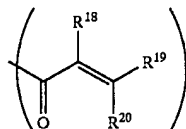
The composition may comprise the poly(arylene ether) in an amount of at least about 10 parts by weight, preferably at least about 15 parts by weight, more preferably at least about 20 parts by weight per 100 parts by weight resin. The composition may comprise the poly(arylene ether) in an amount up to about 50 parts by weight, preferably up to about 45 parts by weight, more preferably up to about 40 parts by weight per 100 parts by weight resin. It will be understood that "100 parts by weight resin" as used herein refers to the combined parts by weight of resinous components such as the poly(arylene ether), the acryloyl monomer, and the allylic monomer; it excludes non-resinous components such as the abrasive filler, and any secondary filler or curing catalyst.

The composition further comprises an acryloyl monomer. The acryloyl monomer comprises at least one acryloyl moiety having the structure



wherein R<sup>16</sup> and R<sup>17</sup> are each independently hydrogen or C<sub>1</sub>-C<sub>12</sub> alkyl, and wherein R<sup>16</sup> and R<sup>17</sup> may be disposed either cis or trans about the carbon-carbon double bond. Preferably, R<sup>16</sup> and R<sup>17</sup> are each independently hydrogen or methyl. In one embodiment, the acryloyl monomer comprises at least two acryloyl moieties having the above structure. In another embodiment, the acryloyl monomer comprises at least three acryloyl moieties having the above structure.

In one embodiment, the acryloyl monomer comprises at least one acryloyl moiety having the structure



wherein R<sup>18</sup>-R<sup>20</sup> are each independently hydrogen, C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub> alkenyl, C<sub>6</sub>-C<sub>18</sub> aryl, C<sub>7</sub>-C<sub>18</sub> mixed (alkyl-aryl), C<sub>2</sub>-C<sub>12</sub> alkoxy carbonyl, C<sub>7</sub>-C<sub>18</sub> aryloxy carbonyl, C<sub>8</sub>-C<sub>18</sub> mixed (alkyl-aryl)oxy carbonyl, nitrile, formyl, carboxylate, imide, thiocarboxylate, or the like. Preferably, R<sup>18</sup>-R<sup>20</sup> are each independently hydrogen or methyl. In one embodiment, the acryloyl monomer comprises at least two acryloyl moieties having the structure above. In another embodiment, the acryloyl monomer comprises at least three acryloyl moieties having the structure above.

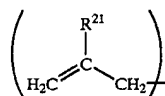
Suitable acryloyl monomers include, for example, methyl (meth)acrylate, ethyl (meth)acrylate, isopropyl (meth)acrylate, n-butyl (meth)acrylate, isobutyl (meth)acrylate, 2-ethylhexyl (meth)acrylate, 2-hydroxyethyl (meth)acrylate, 3-hydroxypropyl (meth)acrylate, hydroxybutyl (meth)acrylate, glycidyl (meth)acrylate, 2,2-dimethyl-3-hydroxypropyl (meth)acrylate, isobornyl (meth)acrylate, tetrahydrofurfuryl (meth)acrylate, 3,4-epoxycyclohexylmethyl (meth)acrylate, and the like; halogenated (meth)acrylates such as pentabromobenzyl (meth)

acrylate, and the like; and acrylic or methacrylic amides such (meth)acrylamide, diacetone (meth)acrylamide, N(2-hydroxyethyl) (meth)acrylamide, N-methyl(meth)acrylamide, N-ethyl(meth)acrylamide, N,N-dimethyl(meth)acrylamide, N,N-dimethylaminopropyl(meth)acrylamide, N,N-dimethylaminopropyl(meth)acrylamide, N,N-dimethylaminoethyl(meth)acrylamide, and the like; and mixtures comprising at least one of the foregoing acryloyl monomers. It will be understood that the suffix (meth)acryl- denotes either acryl- or methacryl-. Additional suitable acryloyl monomers are disclosed in U.S. Provisional Application Serial No. 60/262,571, filed Jan. 18, 2001.

In a preferred embodiment the acryloyl monomer is substantially free of polymerizable moieties other than acryloyl moieties. For example, in this embodiment, the acryloyl monomer may not comprise an allylic moiety, or a vinyl group directly bonded to an aromatic ring.

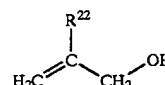
The composition may comprise the acryloyl monomer in an amount of at least about 5 parts by weight, preferably at least about 10 parts by weight, per 100 parts by weight resin. The composition may comprise the poly(arylene ether) in an amount up to about 60 parts by weight, preferably up to about 50 parts by weight, more preferably up to about 40 parts by weight per 100 parts by weight resin.

The composition further comprises an allylic monomer. An allylic monomer is herein defined as a monomer comprising an allylic moiety having the structure



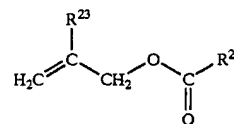
wherein R<sup>21</sup> may be hydrogen, C<sub>1</sub>-C<sub>6</sub> alkyl, or the like. In a preferred embodiment, R<sup>21</sup> is hydrogen. When the allylic monomer comprises at least two allylic moieties, it is termed a polyfunctional allylic monomer.

Allylic monomers may include, for example, allylic alcohols, allyl esters, allyl ethers, and alkoxyated allylic alcohols. Allylic alcohols may have the general structure



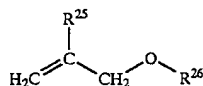
wherein R<sup>22</sup> is hydrogen or C<sub>1</sub>-C<sub>6</sub> alkyl. Suitable allylic alcohols include allyl alcohol, methallyl alcohol, 2-ethyl-2-propen-1-ol, and the like, and mixtures comprising at least one of the foregoing allylic alcohols.

Allyl esters may have the general structure



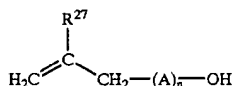
in which R<sup>23</sup> is hydrogen or C<sub>1</sub>-C<sub>6</sub> alkyl, and R<sup>24</sup> is hydrogen or a saturated or unsaturated linear, branched, or cyclic C<sub>1</sub>-C<sub>30</sub> alkyl, aryl, alkylaryl, or aralkyl group. Suitable allyl esters include, for example, allyl formate, allyl acetate, allyl butyrate, allyl benzoate, methallyl acetate, allyl fatty esters, and the like, and mixtures comprising at least one of the foregoing allyl esters.

Allyl ethers may have the general structure



wherein  $\text{R}^{25}$  is hydrogen or  $\text{C}_1\text{--C}_6$  alkyl, and  $\text{R}^{26}$  is a saturated or unsaturated linear, branched, or cyclic  $\text{C}_1\text{--C}_{30}$  alkyl, aryl, alkylaryl, or aralkyl group. Suitable allyl ethers include, for example, allyl methyl ether, allyl ethyl ether, allyl tert-butyl ether, allyl methylbenzyl ether, and the like, and mixtures comprising at least one of the foregoing allyl ethers.

Allylic monomers further include alkoxyated allylic alcohols. Alkoxyated allylic alcohols may have the general structure



wherein  $\text{R}^{27}$  is hydrogen or  $\text{C}_1\text{--C}_6$  alkyl, A is an oxyalkylene group, and n, which is the average number of oxyalkylene groups in the alkoxyated allylic alcohol, has a value from 1 to about 50. Oxyalkylene groups may include oxyethylene, oxypropylene, oxybutylenes, and mixtures comprising at least one of the foregoing oxyalkylene groups. Alkoxyated allylic alcohols can be prepared by reacting an allylic alcohol with up to about 50 equivalents of one or more alkylene oxides in the presence of a basic catalyst as described, for example, in U.S. Pat. Nos. 3,268,561 and 4,618,703. Alkoxyated allylic alcohols can also be made by acid catalysis, as described, for example, in *Journal of the American Chemical Society*, volume 71, pages 1152 ff. (1949).

In a preferred embodiment, the allylic monomer is a polyfunctional allylic monomer. Specific polyfunctional allylic monomers include, for example, diallyl adipate, diallyl citraconate, diallyl diglycolate, diallyl ether, diallyl fumarate, diallyl isophthalate, diallyl itaconate, diallyl maleate, diallyl phthalate, diallyl terephthalate, triallyl aconitate, triallyl cyanurate, triallyl isocyanurate, triallyl phosphate, triallyl trimellitate, tetraallyl o-silicic acid, and the like, and mixtures comprising at least one of the foregoing allylic monomers.

In one embodiment, the allylic monomer is substantially free of polymerizable moieties other than allylic moieties. In this embodiment, the allylic monomer may not comprise, for example, an acryloyl moiety, or a vinyl group directly bonded to an aromatic ring.

The composition may comprise the allylic monomer in an amount of at least about 20 parts by weight, preferably at least about 30 parts by weight, more preferably at least about 40 parts by weight, per 100 parts by weight resin. The composition may comprise the allylic monomer in an amount up to about 80 parts by weight, preferably up to about 70 parts by weight, more preferably up to about 65 parts by weight, per 100 parts by weight resin.

The composition further comprises an abrasive filler. Such fillers may have a Knoop hardness of at least about 2,000, preferably at least about 3,000, more preferably at least about 4,000, yet more preferably at least about 5,000, even more preferably at least about 6,000. Suitable hard fillers may comprise, for example, aluminum oxides; silicon carbides; silicon nitrides; sialons; cubic boron nitrides

(CBN); aluminosilicates; titanium carbides; chromium carbides; tungsten carbides; zirconium oxides; silicon doped boron-aluminum-magnesium (BAM); natural and synthetic diamonds; garnets; composite ceramics comprising at least one of the foregoing fillers; composite ceramic metals (cermet) comprising a metal and at least one of the foregoing fillers, such as, for example, (tungsten carbide+cobalt) and (chromium carbide+nickel); combinations comprising at least one of the foregoing fillers; and the like. Presently preferred abrasive fillers include those comprising diamond, CBN, and/or BAM.

There is no particular limitation on the particle size of the abrasive filler. The abrasive filler may have a particle size corresponding to about 600 mesh to about 5 mesh, preferably about 300 to about 25 mesh, more preferably about 200 to about 80 mesh.

In one embodiment, the abrasive filler comprises a metal coating. The metal coatings may comprise, for example, Ni, Cu, Cr, Fe, Co, Sn, W, Ti, as well as alloys comprising at least one of the foregoing metals, mixtures comprising at least one of the foregoing metals, and the like.

The composition may comprise the abrasive filler in an amount of at least about 5 parts by weight, preferably at least about 50 parts by weight, more preferably at least about 100 parts by weight, yet more preferably at least about 200 parts by weight, ever more preferably at least about 400 parts by weight, per 100 parts by weight resin. The composition may comprise the abrasive filler in an amount of up to about 2,000 parts by weight, preferably up to about 1,000 parts by weight, more preferably up to about 700 parts by weight, per 100 parts by weight resin. One advantage of the curable composition is its ability to allow high filler contents (higher than those permissible with phenolic resins) while maintaining excellent physical properties. Filler amounts may also be expressed as volume percents of the total composition. Thus, the composition may comprise the abrasive filler in an amount of about 5 to about 95 volume percent, preferably about 10 to about 90 volume percent, more preferably about 50 to about 80 volume percent, based on the total volume of the composition.

The composition may, optionally, further comprise secondary fillers. Secondary fillers may include, for example, abrasives such as ceramic borides, including titanium borides; thermal management particles including, for example, powders comprising Cu, Fe, Sn, or bronze, mixtures of the foregoing metallic powders, and the like; additional fillers such as carbon particles, carbon fibers, silicon, and the like, as well as alloys and mixtures comprising at least one of the foregoing secondary fillers. In applications where electrical conductivity or static dissipation is desirable, preferred carbon fibers may include vapor-grown carbon fibers having an average diameter of about 3.5 to about 500 nanometers as described in, for example, U.S. Pat. Nos. 4,565,684 and 5,024,818 to Tibbetts et al.; 4,572,813 to Arakawa; 4,663,230 and 5,165,909 to Tennent; 4,816,289 to Komatsu et al.; 4,876,078 to Arakawa et al.; 5,589,152 to Tennent et al.; and 5,591,382 to Nahass et al. The secondary fillers, when present, may be used in an amount of about 1 to about 30 parts by weight, per 100 parts by weight resin.

The composition may, optionally, further comprise a curing catalyst to increase the curing rate of the unsaturated components. Curing catalysts, also referred to as initiators, are used to initiate the polymerization, cure or crosslink any of numerous thermoplastics and thermosets including unsaturated polyester, vinyl ester and allylic thermosets. Non-limiting examples of curing catalysts are those described in "Plastic Additives Handbook, 4<sup>th</sup> Edition" R. Gachter and H.

Muller (eds.), P. P. Klemchuck (assoc. ed.) Hansen Publishers, New York 1993 and in U.S. Pat. Nos. 5,407,972 to Smith et al., and 5,218,030 to Katayose et al. The curing catalyst for the unsaturated portion of the thermoset would include any compound capable of producing radicals at elevated temperatures. Such curing catalysts may include peroxy and non-peroxy based radical initiators. Examples of useful peroxy initiators include, for example, benzoyl peroxide, dicumyl peroxide, methyl ethyl ketone peroxide, lauryl peroxide, cyclohexanone peroxide, t-butyl hydroperoxide, t-butyl benzene hydroperoxide, t-butyl peroctoate, 2,5-dimethylhexane-2,5-dihydroperoxide, 2,5-dimethyl-2,5-di(t-butylperoxy)-hex-3-yne, di-t-butylperoxide, t-butylcumyl peroxide, alpha,alpha'-bis(t-butylperoxy-m-isopropyl)benzene, 2,5-dimethyl-2,5-di(t-butylperoxy)hexane, dicumylperoxide, di(t-butylperoxy isophthalate, t-butylperoxybenzoate, 2,2-bis(t-butylperoxy)butane, 2,2-bis(t-butylperoxy)octane, 2,5-dimethyl-2,5-di(benzoylperoxy)hexane, di(trimethylsilyl)peroxide, trimethylsilylphenyltriphenylsilyl peroxide, and the like, as well as mixtures comprising at least one of the foregoing curing agents. Typical non-peroxy initiators include, for example, 2,3-dimethyl-2,3-diphenylbutane, 2,3-trimethylsilyloxy-2,3-diphenylbutane, and the like, and mixtures comprising at least one of the foregoing curing catalysts.

Those skilled in the art may determine an appropriate amount of curing catalyst without undue experimentation. The curing catalyst amount may be at least about 0.1 part by weight, preferably at least about 1 part by weight, more preferably at least about 2 part by weight, per 100 parts by weight resin. The curing catalyst amount may be up to about 10 parts by weight, preferably up to about 5 parts by weight, per 100 parts by weight resin. It is preferred that the identity and amount of the curing catalyst be selected so as not to compromise the ability to process or maintain the curable formulation in powder form.

In addition to the components described above, the curable resin composition may further comprise one or more additives such as flame retardants, flame retardant synergists, mold release agents and other lubricants, antioxidants, thermal stabilizers, ultraviolet stabilizers, pigments, dyes, colorants, fibrous reinforcements, disc-shaped fillers, low-aspect ratio fillers, synthetic resins, natural resins, thermoplastic elastomers, and the like, as well as reaction products of the foregoing additives, and mixtures comprising at least one of the foregoing additives. Additive amounts may be determined without undue experimentation. Non-limiting examples of additives are those described in "Plastic Additives Handbook, 4<sup>th</sup> Edition" R. Gachter and H. Muller (eds.), P. P. Klemchuck (assoc. ed.) Hansen Publishers, New York 1993. Many specific additives are also described in U.S. Provisional Application Serial No. 60/262,571, filed Jan. 18, 2001.

In one embodiment, the composition is substantially free of alkenyl aromatic monomers in which an alkenyl substituent is directly bonded to an aromatic ring. By substantially free of alkenyl aromatic monomers, it is meant that such monomers are not intentionally added. Such alkenyl aromatic monomers include, for example, styrene, divinyl benzenes, and vinyl pyridine.

In one embodiment, the composition may be formulated as a powder. For some applications, it may be preferred that the powder be substantially free of particles having any dimension greater than about 300 micrometers, preferably substantially free of particles having any dimension greater than about 150 micrometers, more preferably substantially free of particles having any dimension greater than about

100 micrometers, yet more preferably substantially free of particles having any dimension greater than about 50 micrometers. By substantially free, it is meant that the composition includes less than 5% by weight, preferably less than 2% by weight, more preferably less than 1% by weight of particles having the specified dimensions. In one embodiment, the composition may be formulated as a mixture comprising curable resin particles and abrasive filler particles, with the particle size limitations above applying only to the curable resin particles.

In another embodiment, the composition may be formulated as a pellet using extrusion techniques known in the art.

In order to facilitate handling under ambient conditions and stability of powdered compositions under transportation conditions, it may be preferred that the composition have a melting temperature of at least about 50° C., preferably at least about 60° C., more preferably at least about 70° C. To ensure melting below typical molding temperatures, it may be preferred that the composition have a melting temperature up to about 150° C., preferably up to about 140° C., more preferably up to about 130° C.

In one embodiment, the curable resin composition comprises about 10 to about 50 parts by weight of a poly(arylene ether); about 5 to about 60 parts by weight of an acryloyl monomer; about 20 to about 80 parts by weight of an allylic monomer; and about 5 to about 2,000 parts by weight of an abrasive filler; wherein all parts by weight are based on 100 parts by weight resin.

In one embodiment, the composition comprises about 15 to about 45 parts by weight of a capped poly(arylene ether); about 10 to about 40 parts by weight of a polyfunctional acryloyl monomer; about 30 to about 70 parts by weight of a polyfunctional allylic monomer; and about 100 to about 1,000 parts by weight of an abrasive filler comprising silicon carbide, cubic boron nitride, synthetic diamond, or a mixtures comprising at least one of the foregoing abrasive fillers; wherein all parts by weight are based on 100 parts by weight resin.

It will be understood that the composition encompasses reaction products of any of the above-described curable compositions, as well as articles comprising the cured compositions.

As the composition is defined as comprising multiple components, it will be understood that each component is chemically distinct, particularly in the instance that a single chemical compound may satisfy the definition of more than one component.

There is no particular limitation on the method used to prepare the curable resin composition. In one embodiment, the composition may be prepared by a method comprising blending a poly(arylene ether), an allylic monomer, and an acryloyl monomer to form an intimate blend; and blending the intimate blend and an abrasive filler.

In one embodiment, the composition may be prepared by a method comprising blending a poly(arylene ether) and an allylic monomer to form a first intimate blend; blending the first intimate blend and an acryloyl monomer to form a second intimate blend; processing the second intimate blend to form a curable powder; and blending the curable powder with an abrasive filler. Processing the second intimate blend to form a curable powder may preferably comprise grinding the second intimate blend at a temperature up to about -75° C., preferably up to about -150° C., more preferably up to about -170° C., yet more preferably up to about -190° C. Such temperatures embrittle the resin, thereby facilitating grinding into small particles. For example, the resin may be cryogenically ground by immersing in liquid nitrogen and

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allowing to cool to  $-196^{\circ}\text{C}$ .; it may then be transferred rapidly into the opening of a grinder in a portion-wise fashion where it may contact a rotating screen of the desired mesh size, passing through the mesh to a collection reservoir. Equipment to perform cryogenic grinding is commercially available from, for example, Retsch/Brinkmann as the ZM-1 Grinder. The method may further comprise blending the curable powder with a curing catalyst.

In one embodiment, the composition may be prepared by a method comprising blending about 20 to about 80 parts by weight of an allylic monomer with about 10 to about 50 parts by weight of a poly(arylene ether) to form a first intimate blend; blending the first intimate blend with about 5 to about 60 parts by weight of an acryloyl monomer to form a second intimate blend; grinding the second intimate blend at a temperature up to about  $-75^{\circ}\text{C}$ . to form a first curable powder; blending the first powder with a curing catalyst to form a second curable powder; and blending the second curable powder with about 5 to about 2000 parts by weight of an abrasive filler; wherein all parts by weight are based on 100 parts by weight resin.

Processes useful for processing the composition include injection molding, co-injection molding, reaction injection molding, overmolding, resin transfer molding, vacuum assisted resin transfer molding, Seeman's composite resin infusion manufacturing process (SCRIMP), chemically assisted resin transfer molding, atmospheric pressure molding, open mold casting, wet lay-up, dry lay-up, spray lay-up, sheet molding, bulk molding, filament winding, pultrusion, lamination, and the like, and combinations comprising at least one of the foregoing processes. Additional processes have been described in "Polyesters and Their Applications" by Bjorksten Research Laboratories, Johan Bjorksten (pres.) Henry Tovey (Ch. Lit. Ass.), Betty Harker (Ad. Ass.), James Henning (Ad. Ass.), Reinhold Publishing Corporation, New York, 1956, "Uses of Epoxy Resins", W. G. Potter, Newnes-Buttersworth, London 1975, "Chemistry and Technology of Cyanate Ester Resins" by I. Hamerton, Blakie Academic Publishing an Imprint of Chapman Hall.

There is no particular limitation on the method by which the composition may be cured. The composition may, for example, be cured thermally or by using irradiation techniques, including UV irradiation and electron beam irradiation.

In one embodiment, the resin composition may be formulated as a powder. In this form, it is useful for mixing with other powdered additives to form a dry mix, in that blending is accomplished more readily than when the resin composition is a viscous liquid or paste. Use of the powdered resin composition is particularly advantageous when the adhesive filler comprises the majority of the blend, for example about 70 to about 80 weight percent of the total composition, the balance including the curable resin.

In another embodiment, the resin composition may be formulated as a pellet or other solid form derived from compounding. Compounding procedures known in the art may be useful to improve dispersion and wetting of the abrasive filler, compared to dispersion and wetting achieved with dry powder mixing methods. Dispersion and wetting of abrasive fillers may also be improved by the use of coatings applied to the abrasive filler.

Articles formed using the above processes may be post-mold processed, such as, for example, ground to a particular size or shape, sharpened, annealed, fixtured, or the like. In fact, there is no reason that blades comprising the cured resin composition cannot be sharpened in use. For example, a lawnmower blade comprising the cured resin composition may be sharpened should the blade become dull or nicked

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during use. There is virtually no restriction as to the parts that can be made from the curable and cured resin compositions. Presently preferred articles comprising the cured composition include cut-off wheels and grinding wheels, and the like. For example, cut-off wheels molded from the curable resin composition may exhibit a G ratio of at least about 300, preferably at least about 400, more preferably at least about 500, as measured on cemented tungsten carbide, where G ratio is the ratio (volume of work piece removed)/(volume of wheel consumed) as described in "Metals Handbook; Ninth Edition; Volume 16—Machining" ASM International, page 422 (1989). A specific procedure for determining G ratio values is given in the following examples.

The curable and cured resin compositions are further illustrated by the following non-limiting examples.

#### EXAMPLE 1

This example describes the preparation of a powdered resin material. Diallyl phthalate (510 grams; obtained from Aldrich as a liquid of 97% purity) was heated to  $160\text{--}165^{\circ}\text{C}$ . in a glass reaction vessel. To this was added methacrylate-capped poly(2,6-dimethyl-1,4-phenylene ether) (PPE-MA; 340 grams) having an intrinsic viscosity of 0.25 dL/g as measured at  $25^{\circ}\text{C}$ . in chloroform. The capped poly(arylene ether) was prepared by reaction of the corresponding uncapped poly(arylene ether) with methacrylic anhydride, using procedures described in U.S. patent application Ser. No. 09/440,747, filed Nov. 16, 1999. The mixture was stirred and heated until the poly(arylene ether) completely dissolved. Trimethylolpropane trimethacrylate (TMPTMA; 150 grams; obtained from Sartomer as a neat liquid) was then added to the reaction flask and mixed until it was completely blended. The solution was then poured into a flat container and allowed to cool so that it could form a hardened, wax-like substance. The resin mixture was cooled to  $-196^{\circ}\text{C}$ . in liquid nitrogen and rapidly transferred to a Retsch/Brinkmann as the ZM-1 Grinder where it was ground to produce a powdered resin having particle sizes less than about 50 grit. To the powdered resin was then added an initiator, dicumyl peroxide, at 2 weight percent based on total resin weight.

#### EXAMPLE 2

This example describes the preparation of a curable composition including an abrasive filler. Twenty parts by weight of the powdered resin of Example 1 were combined with 48.5 parts by weight of nickel-coated diamond having 44 weight percent diamond and 56 weight percent nickel, and 31.5 parts by weight of silicon carbide. The nickel-coated diamond had a mesh size of 120–140. The above mixture was placed in a mold having a cavity of nominal dimensions 7 centimeter diameter by 1 centimeter thickness. The mold was then closed and heated to  $140^{\circ}\text{C}$ . as a force of 3 metric tons was applied to compress the resin/abrasive mixture. After 25 minutes, the specimen was removed from the mold and examined. A hardened, crosslinked, disk having good physical integrity was obtained. The sample exhibited a hardness using Rockwell indenter H of 91, a density by the Archimedes method of 100% (no porosity), and a room temperature thermal conductivity of 3.6 watts per meter per Kelvin (W/m/K) indicating complete wetting and adhesion of diamond and silicon carbide grits by resin.

#### EXAMPLE 3

This example describes the preparation of a curable composition including multiple abrasive fillers, as well as secondary fillers. Eighteen parts by weight of the powdered resin of Example 1 were combined with 27 parts by weight

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diamond grit having a mesh size of about 120, 35 parts by weight of the nickel-coated diamond of Example 2, 12 parts by weight of titanium boride fines having a mesh size of about -500, and 8 parts by weight of metallic copper fines having a mesh size of about -500. This mixture was placed into a mold having a cavity of nominal dimensions 7 centimeters diameter by 1 centimeter thickness. The mold was closed and heated to 155° C. as a force of 6 metric tons was applied to compress the resin/abrasive mixture. After 30 minutes, the specimen was removed from the mold and examined. A hardened, crosslinked disk having good physical integrity was obtained. The molded disk had a Barcol hardness of 66. The disk was post-cured for 20 hours at 150° C. The post-cured disk had a Barcol hardness of 73.

## EXAMPLES 4 AND 5

These examples describe the use of an abrasive-filled composition to mold A1A abrasive cut-off wheels using two curing conditions. The abrasive-filled curable composition of Example 3 was compression molded at a temperature of about 350–375° F. and a pressure of about 20 ton/in<sup>2</sup> for 60 minutes to yield a 1A1 cut-off wheel having a wheel diameter of 177.8 millimeters (7.0 inches), a wheel rim width of 6.4 millimeters (0.250 inches), and an abrasive rim depth of 6.4 millimeters (0.250 inches). This grinding wheel corresponds to Example 4, and it had a bond density of 3.384 g/cc and an Rockwell Hardness H scale (HRH) value of 68–74.

The composition and procedure used to prepare Example 4 was used to prepare Example 5, except that the curing temperature was increased to about 700–750° F. and the pressure was increased to 15 ton/in<sup>2</sup>. This grinding wheel had a bond density of 3.297 g/cc and an HRH value of 100–110.

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TABLE 1-continued

Dress Plunge Rate	8 inch/min
Dress Amount	0.30 in <sup>3</sup>
<b>FINISH TRUING</b>	
Finish Truing Device	Brake
Finish Truing Wheel	3.0 inch diameter × 0.090 inch wide MBS-750 Metal-Bond Diamond wheel
Mesh size	60/80
Concentration	10 volume %
Truing Conditions	0.0001 inch downfeed × 16.0 inch/min crossfeed
Number of Passes	6
<b>GRINDING TEST CONDITIONS</b>	
Machine	Brown & Sharpe model 8/24, 15 hp CNC surface grinder
Grind Mode	Creepfeed (upcut)
Wheel Speed	5,500 feet/min (28 m/sec)
Depth of Cut	0.040 inch (1.0 mm)
Table Speed	7.5 inch/min (2.3 m/min)
Width of Cut	0.140 inch (3.6 mm)
Length of Cut	3.50 inch (89 mm)
Material Removal Rate	0.30 in <sup>3</sup> /min (3.2 mm <sup>3</sup> /mm/sec)
Workpiece Material Size	3.5 inch long × 0.140 inch wide (89 mm × 3.6 mm)
Coolant	Master Chemical VHPE 320 water soluble oil at 5% concentration
Coolant Flow	24 gallons/min at 100 psi (entry and exit nozzles)

TABLE 2

Designations							Properties			
							Compositions (Wt. %)			Density
ISO	US		WC	TiC	Ta(Nb)	Co	g/cm <sup>3</sup>	Size μm	HRA	Strength (psi)
Symbol	Code	Equiv.								
T-11	P30	C5	72	11.5	8.5	8.5	12.4	2	91.4	250,000

Cut-off wheels were tested using tungsten carbide (WC) material. Wheel preparation and test conditions are summarized in Table 1. The composition and properties of the WC material are summarized in Table 2. Compositions, molding temperatures, and test results for the cut-off wheels are given in Table 3.

TABLE 1

**ROUGH TRUING**

Rough Truing Device     Brake  
Rough Truing     3.0 inch diameter × 1.0 inch wide 37C60  
MVK Silicon Wheel Carbide wheel  
Rough Truing     0.0002 inch - 0.0020 inch downfeed × 21.0  
Conditions     inch/min crossfeed

**WHEEL DRESSING**

Dressing Stick     Bay State 1.0 inch × 1.0 inch Aluminum  
Oxide #9A240G9V82  
Dress Mode     Plunge

TABLE 3

	Example 3	Example 4
<b>COMPOSITION</b>		
diallyl phthalate (pbw)	51	51
PPE-MA (pbw)	34	34
TMPTMA (pbw)	15	15
dicumyl peroxide	2	2
diamond	150	150
nickel-coated diamond	194	194
titanium boride	67	67
copper	44	44
CURING TEMPERATURE (° F)	350–375	700–750
<b>PROPERTIES</b>		
G-ratio, 1 in <sup>3</sup>	393	583
Power (kW)	1.9	2.1
Ra (micrometer-inch)	21	13

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The results in Table 1 show that cut-off wheels prepared from the curable resin composition exhibit low wear rate, high free-cutting capability, and excellent surface finish.

While the invention has been described with reference to a preferred embodiment, it will be understood by those skilled in the art that various changes may be made and equivalents may be substituted for elements thereof without departing from the scope of the invention. In addition, many modifications may be made to adapt a particular situation or material to the teachings of the invention without departing from essential scope thereof. Therefore, it is intended that the invention not be limited to the particular embodiment disclosed as the best mode contemplated for carrying out this invention, but that the invention will include all embodiments falling within the scope of the appended claims.

All cited patents and other references are incorporated herein by reference in their entirety.

What is claimed is:

1. A curable resin composition, comprising:

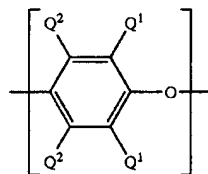
a poly(arylene ether);

an acryloyl monomer;

an allylic monomer; and

an abrasive filler selected from the group consisting of silicon carbides; silicon nitrides; sialons; cubic boron nitrides; aluminosilicates; titanium carbides; chromium carbides; tungsten carbides; zirconium oxides; silicon doped boron-aluminum-magnesium; natural and synthetic diamonds; garnets; composite ceramics comprising at least one of the foregoing abrasive fillers; composite ceramic metals comprising a metal and at least one of the foregoing abrasive fillers; and combinations comprising at least one of the foregoing abrasive fillers.

2. The curable resin composition of claim 1, wherein the poly(arylene ether) comprises a plurality of structural units of the formula



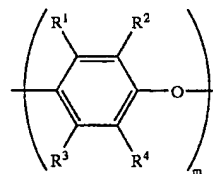
wherein for each structural unit, each Q<sup>1</sup> is independently selected from the group consisting of halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarbonoxy, and C<sub>1</sub>-C<sub>12</sub> halohydrocarbonoxy wherein at least two carbon atoms separate the halogen and oxygen atoms; and each Q<sup>2</sup> is independently selected from the group consisting of hydrogen, halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarbonoxy, and C<sub>2</sub>-C<sub>12</sub> halohydrocarbonoxy wherein at least two carbon atoms separate the halogen and oxygen atoms.

3. The curable resin composition of claim 1, wherein the poly(arylene ether) has a free hydroxyl group content less than about 500 micrograms per gram.

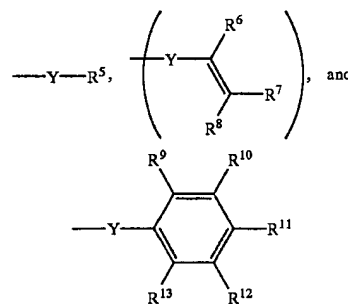
4. The curable resin composition of claim 1, wherein the poly(arylene ether) comprises a capped poly(arylene ether) having the structure Q-(J-K),

wherein Q is the residuum of a monohydric, dihydric, or polyhydric phenol; y is 1 to 100; J comprises recurring units having the structure

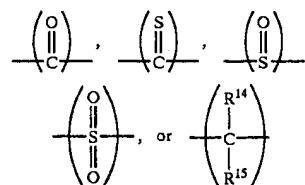
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wherein R<sup>1</sup>-R<sup>4</sup> are each independently selected from the group consisting of hydrogen, halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub> alkenyl, C<sub>2</sub>-C<sub>12</sub> alkynyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydroxyalkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarbonoxy, and C<sub>2</sub>-C<sub>12</sub> halohydrocarbonoxy wherein at least two carbon atoms separate the halogen and oxygen atoms; m is 1 to about 200; and K is a capping group selected from the group consisting of

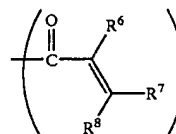


wherein R<sup>5</sup> is C<sub>1</sub>-C<sub>12</sub> alkyl; R<sup>6</sup>-R<sup>8</sup> are each independently selected from the group consisting of hydrogen, C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub> alkenyl, C<sub>6</sub>-C<sub>18</sub> aryl, C<sub>7</sub>-C<sub>18</sub> mixed (alkyl-aryl), C<sub>2</sub>-C<sub>12</sub> alkoxy carbonyl, C<sub>7</sub>-C<sub>18</sub> aryloxy carbonyl, C<sub>8</sub>-C<sub>18</sub> mixed (alkyl-aryl)oxy carbonyl, nitrile, formyl, carboxylate, imide, and thiocarboxylate; R<sup>9</sup>-R<sup>13</sup> are each independently selected from the group consisting of hydrogen, halogen, C<sub>1</sub>-C<sub>12</sub> alkyl, hydroxy, and amino; and wherein Y is a divalent group selected from the group consisting of



wherein R<sup>14</sup> and R<sup>15</sup> are each independently selected from the group consisting of hydrogen and C<sub>1</sub>-C<sub>12</sub> alkyl.

5. The curable resin composition of claim 4, wherein the capped poly(arylene ether) comprises a capping group having the structure

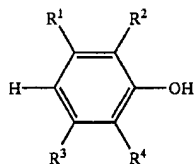


wherein R<sup>6</sup>-R<sup>8</sup> are each independently selected from the group consisting of hydrogen, C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub>

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alkenyl, C<sub>6</sub>-C<sub>18</sub> aryl, C<sub>7</sub>-C<sub>18</sub> mixed (alkyl-aryl), C<sub>2</sub>-C<sub>12</sub> alkoxycarbonyl, C<sub>7</sub>-C<sub>18</sub> aryloxy carbonyl, C<sub>8</sub>-C<sub>18</sub> mixed (alkyl-aryl)oxycarbonyl, nitrile, formyl, carboxylate, imide, and thiocarboxylate.

6. The curable resin composition of claim 4, wherein the capped poly(arylene ether) is prepared by capping a poly(arylene ether) consisting essentially of the polymerization product of at least one monohydric phenol having the structure

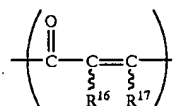


wherein R<sup>1</sup>-R<sup>4</sup> are each independently selected from the group consisting of hydrogen, halogen, primary or secondary C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub> alkenyl, C<sub>2</sub>-C<sub>12</sub> alkynyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydroxyalkyl, phenyl, C<sub>1</sub>-C<sub>12</sub> haloalkyl, C<sub>1</sub>-C<sub>12</sub> aminoalkyl, C<sub>1</sub>-C<sub>12</sub> hydrocarboxy, and C<sub>2</sub>-C<sub>12</sub> halohydrocarboxy wherein at least two carbon atoms separate the halogen and oxygen atoms.

7. The curable resin composition of claim 1, wherein the poly(arylene ether) has an intrinsic viscosity of about 0.1 to about 0.5 deciliters/gram in chloroform at 25° C.

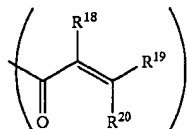
8. The curable resin composition of claim 1, comprising about 10 to about 50 parts by weight of the poly(arylene ether) per 100 parts by weight resin.

9. The curable resin composition of claim 1, wherein the acryloyl monomer comprises at least one acryloyl moiety having the structure



wherein R<sup>16</sup> and R<sup>17</sup> are each independently selected from the group consisting of hydrogen and C<sub>1</sub>-C<sub>12</sub> alkyl, and wherein R<sup>16</sup> and R<sup>17</sup> may be disposed either cis or trans about the carbon-carbon double bond.

10. The curable resin composition of claim 1, wherein the acryloyl monomer comprises at least one acryloyl moiety having the structure



wherein R<sup>18</sup>-R<sup>20</sup> are each independently selected from the group consisting of hydrogen, C<sub>1</sub>-C<sub>12</sub> alkyl, C<sub>2</sub>-C<sub>12</sub> alkenyl, C<sub>6</sub>-C<sub>18</sub> aryl, C<sub>7</sub>-C<sub>18</sub> mixed (alkyl-aryl), C<sub>2</sub>-C<sub>12</sub> alkoxycarbonyl, C<sub>7</sub>-C<sub>18</sub> aryloxy carbonyl, mixed C<sub>8</sub>-C<sub>18</sub> (alkyl-aryl)oxycarbonyl, nitrile, formyl, carboxylate, imide, and thiocarboxylate.

11. The curable resin composition of claim 10, wherein the acryloyl monomer comprises at least two acryloyl moieties.

12. The curable resin composition of claim 1, wherein the acryloyl monomer is selected from the group consisting of trimethylolpropane trimethacrylate, trimethylolpropane

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triacrylate, 1,6-hexanediol dimethacrylate, 1,6-hexanediol diacrylate, ethylene glycol dimethacrylate, ethylene glycol diacrylate, propylene glycol dimethacrylate, propylene glycol diacrylate, cyclohexanedimethanol dimethacrylate, cyclohexanedimethanol diacrylate, butanediol dimethacrylate, butanediol diacrylate, diethylene glycol dimethacrylate, diethylene glycol diacrylate, triethylene glycol dimethacrylate, triethylene glycol diacrylate, isobornyl methacrylate, isobornyl acrylate, methyl methacrylate, methyl acrylate, and mixtures comprising at least one of the foregoing acryloyl monomers.

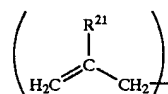
13. The curable resin composition of claim 1, wherein the acryloyl monomer is selected from the group consisting of trimethylolpropane trimethacrylate, trimethylolpropane triacrylate, and mixtures comprising at least one of the foregoing acryloyl monomers.

14. The curable resin composition of claim 1, wherein the acryloyl monomer is substantially free of polymerizable moieties other than acryloyl moieties.

15. The curable resin composition of claim 1, comprising about 5 to about 60 parts by weight of the acryloyl monomer per 100 parts by weight resin.

16. The curable resin composition of claim 1, comprising about 5 to about 40 parts by weight of the acryloyl monomer per 100 parts by weight resin.

17. The curable resin composition of claim 1, wherein the allylic monomer comprises an allylic moiety having the structure



wherein R<sup>21</sup> is selected from the group consisting of hydrogen and C<sub>1</sub>-C<sub>6</sub> alkyl.

18. The curable resin composition of claim 17, wherein the allylic monomer comprises at least two allylic moieties.

19. The curable resin composition of claim 1, wherein the allylic monomer is selected from the group consisting of allyl alcohol, methallyl alcohol, 2-ethyl-2-propen-1-ol, allyl formate, allyl acetate, allyl butyrate, allyl benzoate, methallyl acetate, allyl fatty esters, allyl methyl ether, allyl ethyl ether, allyl tert-butyl ether, allyl methylbenzyl ether, alkoxy-ated allylic alcohols, diallyl adipate, diallyl citraconate, diallyl diglycolate, diallyl ether, diallyl fumarate, diallyl isophthalate, diallyl itaconate, diallyl maleate, diallyl phthalate, diallyl terephthalate, triallyl aconitate, triallyl cyanurate, triallyl isocyanurate, triallyl phosphate, triallyl trimellitate, tetraallyl o-silicic acid, and mixtures comprising at least one of the foregoing allylic monomers.

20. The curable resin composition of claim 1, wherein the allylic monomer is selected from the group consisting of diallyl adipate, diallyl citraconate, diallyl diglycolate, diallyl ether, diallyl fumarate, diallyl isophthalate, diallyl itaconate, diallyl maleate, diallyl phthalate, diallyl terephthalate, triallyl aconitate, triallyl cyanurate, triallyl isocyanurate, triallyl phosphate, triallyl trimellitate, tetraallyl o-silicic acid, and mixtures comprising at least one of the foregoing allylic monomers.

21. The curable resin composition of claim 1, wherein the allylic monomer comprises diallyl phthalate.

22. The curable resin composition of claim 1, wherein the allylic monomer is substantially free of polymerizable moieties other than allylic moieties.

23. The curable resin composition of claim 1, comprising about 20 to about 80 parts by weight of the allylic monomer per 100 parts by weight resin.

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24. The curable resin composition of claim 1, wherein the abrasive filler has a Knoop hardness of at least about 2,000.

25. The curable resin composition of claim 1, wherein the abrasive filler has a mesh size of about 600 to about 5.

26. The curable resin composition of claim 1, wherein the abrasive filler comprises a metal coating.

27. The curable resin composition of claim 26, wherein the metal coating comprises a metal selected from the group consisting of Ni, Cu, Cr, Fe, Co, Sn, W, Ti, alloys comprising at least one of the foregoing metals, and mixtures comprising at least one of the foregoing metals.

28. The curable resin composition of claim 1, wherein the abrasive filler is selected from the group consisting of silicon carbides; cubic boron nitrides; natural and synthetic diamonds; composite ceramic metals comprising a metal and at least one of the foregoing fillers; and combinations comprising at least one of the foregoing abrasive fillers.

29. The curable resin composition of claim 1, comprising up to about 2,000 parts by weight of the abrasive filler per 100 parts by weight resin.

30. The curable resin composition of claim 1, comprising at least about 5 parts by weight of the abrasive filler per 100 parts by weight resin.

31. The curable resin composition of claim 1, comprising at least about 300 parts by weight of the abrasive filler per 100 parts by weight resin.

32. The curable resin composition of claim 1, comprising at least about 400 parts by weight of the abrasive filler per 100 parts by weight resin.

33. The curable resin composition of claim 1, further comprising a secondary filler selected from the group consisting of ceramic borides, Cu, Fe, Sn, bronze, C, silica, alumina, Si, and mixtures comprising at least one of the foregoing secondary fillers.

34. The curable resin composition of claim 1, further comprising a curing catalyst.

35. The curable resin composition of claim 34, wherein the curing catalyst is selected from the group consisting of benzoyl peroxide, dicumyl peroxide, methyl ethyl ketone peroxide, lauryl peroxide, cyclohexanone peroxide, t-butyl hydroperoxide, t-butyl benzene hydroperoxide, t-butyl peroctoate, 2,5-dimethylhexane-2,5-dihydroperoxide, 2,5-dimethyl-2,5-di(t-butylperoxy)-hex-3-yne, di-t-butylperoxide, t-butylcumyl peroxide, alpha,alpha'-bis(t-butylperoxy-m-isopropyl)benzene, 2,5-dimethyl-2,5-di(t-butylperoxy)hexane, dicumylperoxide, di(t-butylperoxy isophthalate, t-butylperoxybenzoate, 2,2-bis(t-butylperoxy) butane, 2,2-bis(t-butylperoxy)octane, 2,5-dimethyl-2,5-di (benzoylperoxy)hexane, di(trimethylsilyl)peroxide, trimethylsilylphenyltriphenylsilyl peroxide, 2,3-dimethyl-2,3-diphenylbutane, 2,3-trimethylsilyloxy-2,3-diphenylbutane, and mixtures comprising at least one of the foregoing curing catalysts.

36. The curable resin composition of claim 34, comprising about 0.1 to about 10 parts by weight of the curing catalyst per 100 parts by weight resin.

37. The curable resin composition of claim 1, further comprising an additive selected from the group consisting of flame retardants, flame retardant synergists, mold release agents and other lubricants, antioxidants, thermal stabilizers, ultraviolet stabilizers, pigments, dyes, colorants, anti-static agents, fibrous reinforcements, disc-shaped fillers, low-aspect ratio fillers, synthetic resins, natural resins, thermoplastic elastomers, and mixtures comprising at least one of the foregoing additives.

38. The curable resin composition of claim 1, wherein the composition is substantially free of alkenyl aromatic monomers in which an alkenyl substituent is directly bonded to an aromatic ring.

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39. The curable resin composition of claim 1, having a melting point of about 50° C. to about 150° C.

40. The curable resin composition of claim 1, in the form of a powder.

41. The curable resin composition of claim 40, wherein the powder is substantially free of non-abrasive particles having any dimension greater than about 300 micrometers.

42. The curable resin composition of claim 1, in the form of a pellet.

43. A curable resin composition, comprising:  
about 10 to about 50 parts by weight of a poly(arylene ether);

about 5 to about 60 parts by weight of an acryloyl monomer;

about 20 to about 80 parts by weight of an allylic monomer; and

about 5 to about 2,000 weight percent of an abrasive filler selected from the group consisting of silicon carbides; silicon nitrides; sialons; cubic boron nitrides; aluminosilicates; titanium carbides; chromium carbides; tungsten carbides; zirconium oxides; silicon doped boron-aluminum-magnesium; natural and synthetic diamonds; garnets; composite ceramics comprising at least one of the foregoing abrasive fillers; composite ceramic metals comprising a metal and at least one of the foregoing abrasive fillers; and combinations comprising at least one of the foregoing abrasive fillers; wherein all parts by weight are based on 100 parts by weight resin.

44. A curable resin composition, comprising:  
about 15 to about 45 parts by weight of a capped poly(arylene ether);

about 10 to about 40 parts by weight of a polyfunctional acryloyl monomer;

about 30 to about 70 parts by weight of a polyfunctional allylic monomer; and

about 100 to about 1,000 parts by weight of an abrasive filler comprising  
silicon carbide, cubic boron nitride, or synthetic diamond;  
wherein all parts by weight are based on 100 parts by weight resin.

45. A cured resin composition, comprising the reaction product of:

a poly(arylene ether);

an acryloyl monomer;

an allylic monomer; and

an abrasive filler selected from the group consisting of silicon carbides; silicon nitrides; sialons; cubic boron nitrides; aluminosilicates; titanium carbides; chromium carbides; tungsten carbides; zirconium oxides; silicon doped boron-aluminum-magnesium; natural and synthetic diamonds; garnets; composite ceramics comprising at least one of the foregoing abrasive fillers; composite ceramic metals comprising a metal and at least one of the foregoing abrasive fillers; and combinations comprising at least one of the foregoing abrasive fillers.

46. A method of preparing a curable resin composition, comprising:

blending a poly(arylene ether), an allylic monomer, and an acryloyl monomer to form an intimate blend; and

blending the intimate blend and an abrasive filler selected from the group consisting of silicon carbides; silicon nitrides; sialons; cubic boron nitrides; aluminosilicates;



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titanium carbides; chromium carbides; tungsten carbides; zirconium oxides; silicon doped boron-aluminum-magnesium; natural and synthetic diamonds; garnets; composite ceramics comprising at least one of the foregoing abrasive fillers; composite ceramic metals comprising a metal and at least one of the foregoing abrasive fillers; and combinations comprising at least one of the foregoing abrasive fillers.

47. A method of preparing a curable resin composition, comprising:

blending a poly(arylene ether) and an allylic monomer to form a first intimate blend;

blending the first intimate blend and an acryloyl monomer to form a second intimate blend;

processing the second intimate blend to form a curable powder; and

blending the curable powder with an abrasive filler.

48. The method of claim 47, wherein processing the second intimate blend to form a curable powder comprises grinding at a temperature up to about  $-75^{\circ}\text{C}$ .

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49. The method of claim 47, further comprising blending the curable powder with a curing catalyst.

50. A method of preparing a curable resin composition, comprising:

blending about 20 to about 80 parts by weight of an allylic monomer with about 10 to about 50 parts by weight of a poly(arylene ether) to form a first intimate blend;

blending the first intimate blend with about 5 to about 60 parts by weight of an acryloyl monomer to form a second intimate blend;

grinding the second intimate blend at a temperature less than about  $-75^{\circ}\text{C}$ . to form a first curable powder;

blending the first powder with a curing catalyst to form a second curable powder; and

blending the second curable powder with about 5 to about 2000 parts by weight of an abrasive filler;

wherein all parts by weight are based on 100 parts by weight resin.

\* \* \* \* \*